

IoT



FlexEnable

Bringing Every Surface to Life

Professor Henning Sirringhaus – Co-Founder
Chuck Milligan – CEO

Wearables



Automotive



Sensors



Displays

The Plastic Logic / Flexenable Journey

Technology

Product

Technology Platform



Spun out of Cambridge University

2000

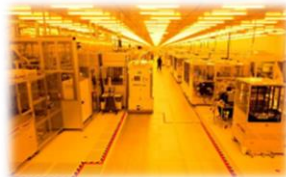


Plastic Logic Founded Nov 2000



1.2M organic transistors

2005

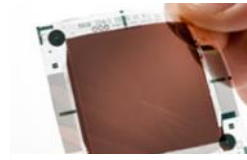


Plastic Logic Process Proven Industrially



Color Industrialized

2010



Worlds 1st All organic image sensor

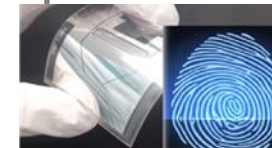
Distortion-free backplane process demonstrated

2014

Vertical TFT demonstrated



Flex AMOLED Demonstrated



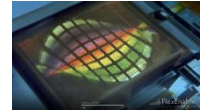
Flex Fingerprint Sensor Demonstrated



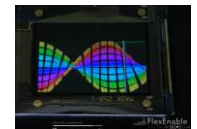
Plastic LCD – announced February 2015 – partnership with Merck

2015

FlexEnable Founded, February 2015



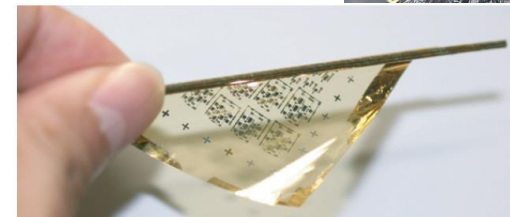
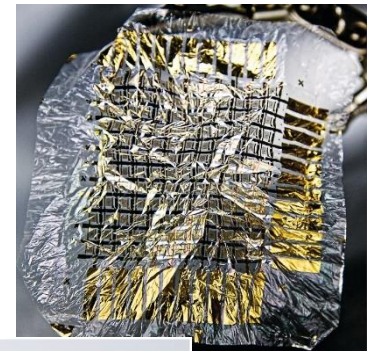
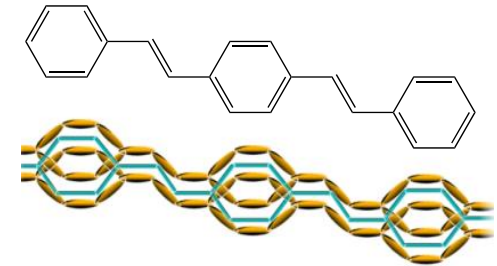
March 2015 - Colour, Video Rate plastic OLED



April 2015 - Colour, Video rate Plastic LCD display

Organic semiconductors

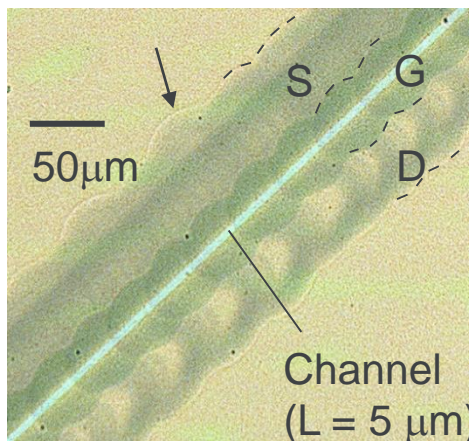
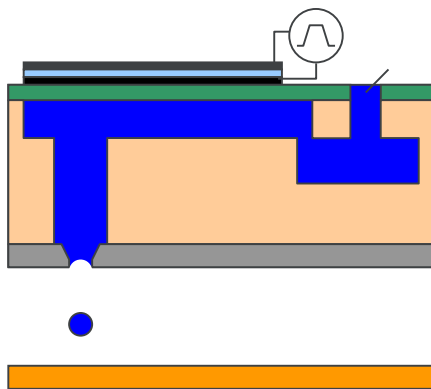
- Exhibit semiconducting properties similar to silicon; Can be used in optoelectronic devices (OLED, solar cells, **transistors**)
- Compatibility with large-area, solution-processing and printing
- Inherently low-temperature, flexible / plastic materials
- **Enabling electronics on low-temperature flexible substrates**



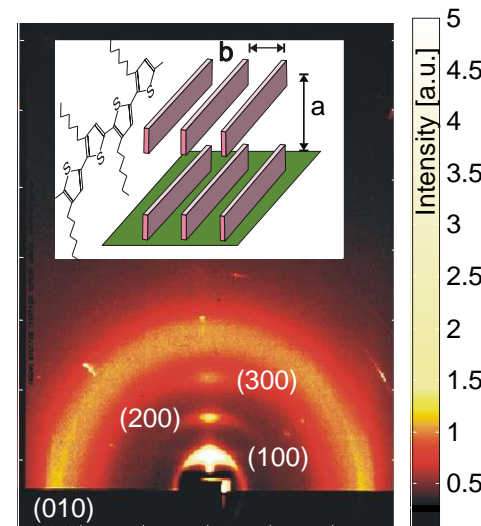
Sekitani et al., Nat. Mat. 9, 1015 (2010)

Research breakthroughs in Cavendish Laboratory (1999/2000) - Inkjet printed organic transistors

Printing-based manufacturing



Science 290, 2123 (2000)



Higher carrier mobilities through self-organisation

Nature 401, 685 (1999)

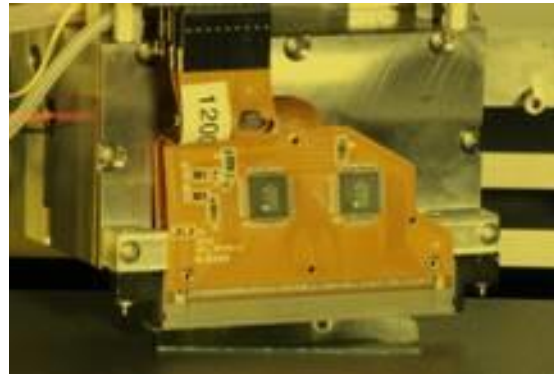
- Spin-off company Plastic Logic founded in 2000 with 6 patents/patent applications
- Early-stage materials technology with wide range of potential but unproven applications

Considerations at the start

- Strong IP position with clear IP ownership.
- Is timing right ?
 - Commercial focus needed - Need to build a strong, engineering team.
- Solution to a problem ?
 - Emerging interest in flexible displays/electronics
- Support from Technology Transfer Office, local VCs & lawyers.
- Market focus ?
 - Flexible displays with an active matrix of transistors

Technology development in Cambridge (2001-2006)

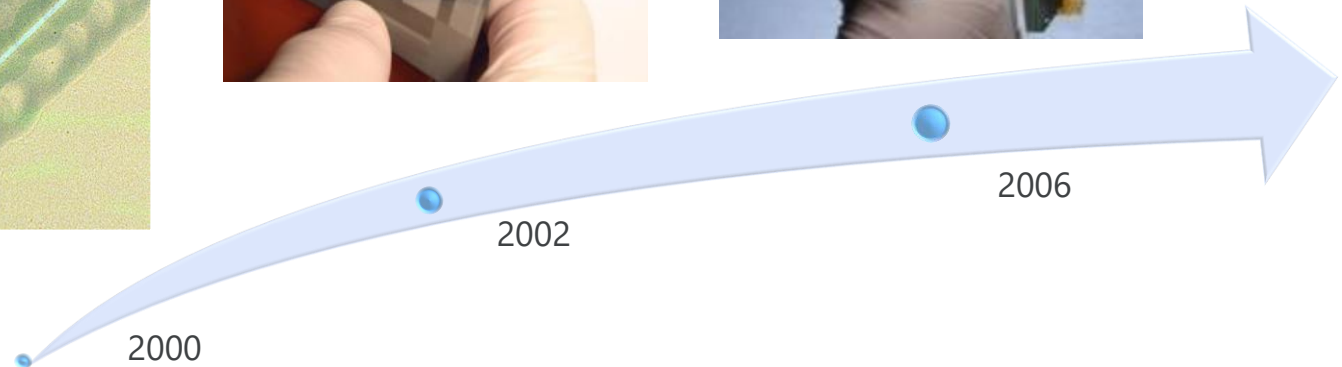
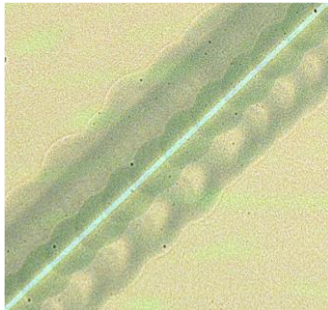
- With venture capital seed investment we built flexible electronics/display prototyping line (14" substrate capability, manual substrate handling)



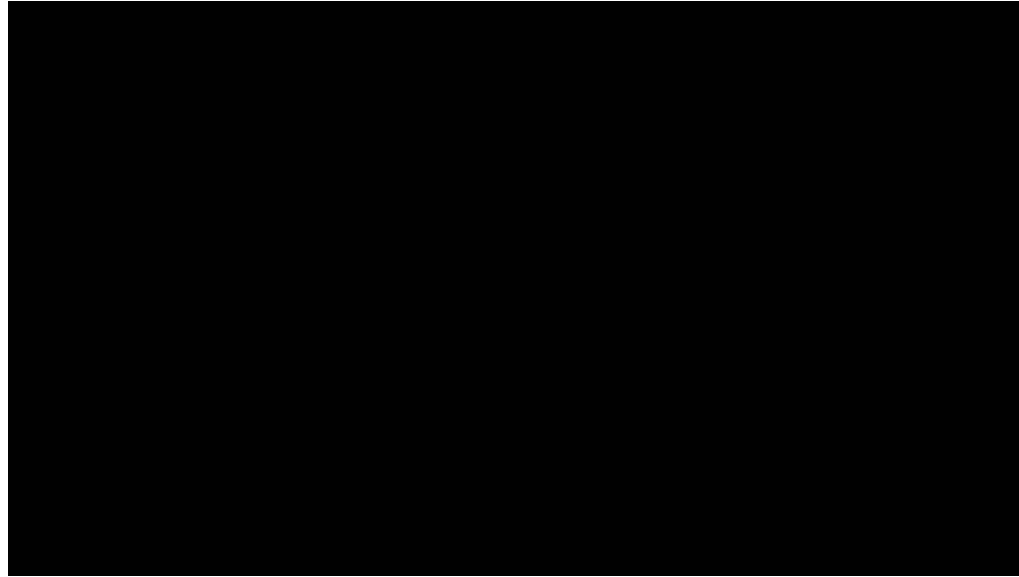
Technology development in Cambridge (2001-2006)

From ten to a million transistors

- Transition from science to process engineering
 - Use available manufacturing equipment whenever possible
 - Invent only where necessary
- First industrial partnership projects



A big decision (2006) – Investment in manufacturing plant



- Raised \$100 million from mainly US – based venture capital funds
- To built world's first flexible display manufacturing plant (Generation 3.5, fully automated)
- Location – Dresden, "Silicon Saxony" (Germany)

A second big, near fatal decision (2006) – Design of own consumer electronics product

The QUE - An Innovative eReader unlike any other



- Large Display Optimal for Branded Content
- Thin and Light Weight
- Rugged – Will Not Break Like Glass
- Intuitive Touch Screen Interface
- Simple Access to Published Content
- Captures Advertising Opportunity
- Content Partnerships

Failure of the product (2010)



- Launch of QUE at CES (Jan 9 2010) – voted one of top 10 gadgets of show

- Delays in establishing stable production
- Apple launched iPad (Jan 27, 2010)

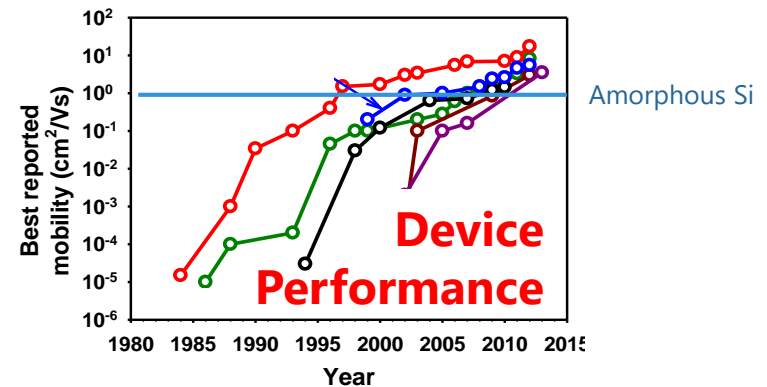
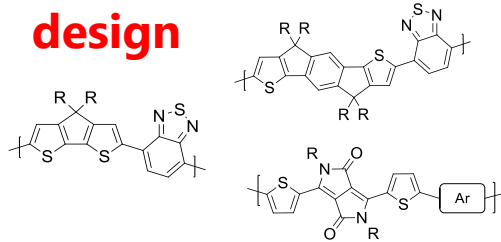


What saved the company ?

- Technology worked
 - Manufacturing yields and reliability of flexible displays as high as in conventional silicon-based display manufacturing
- Improvements in materials performance



Materials design

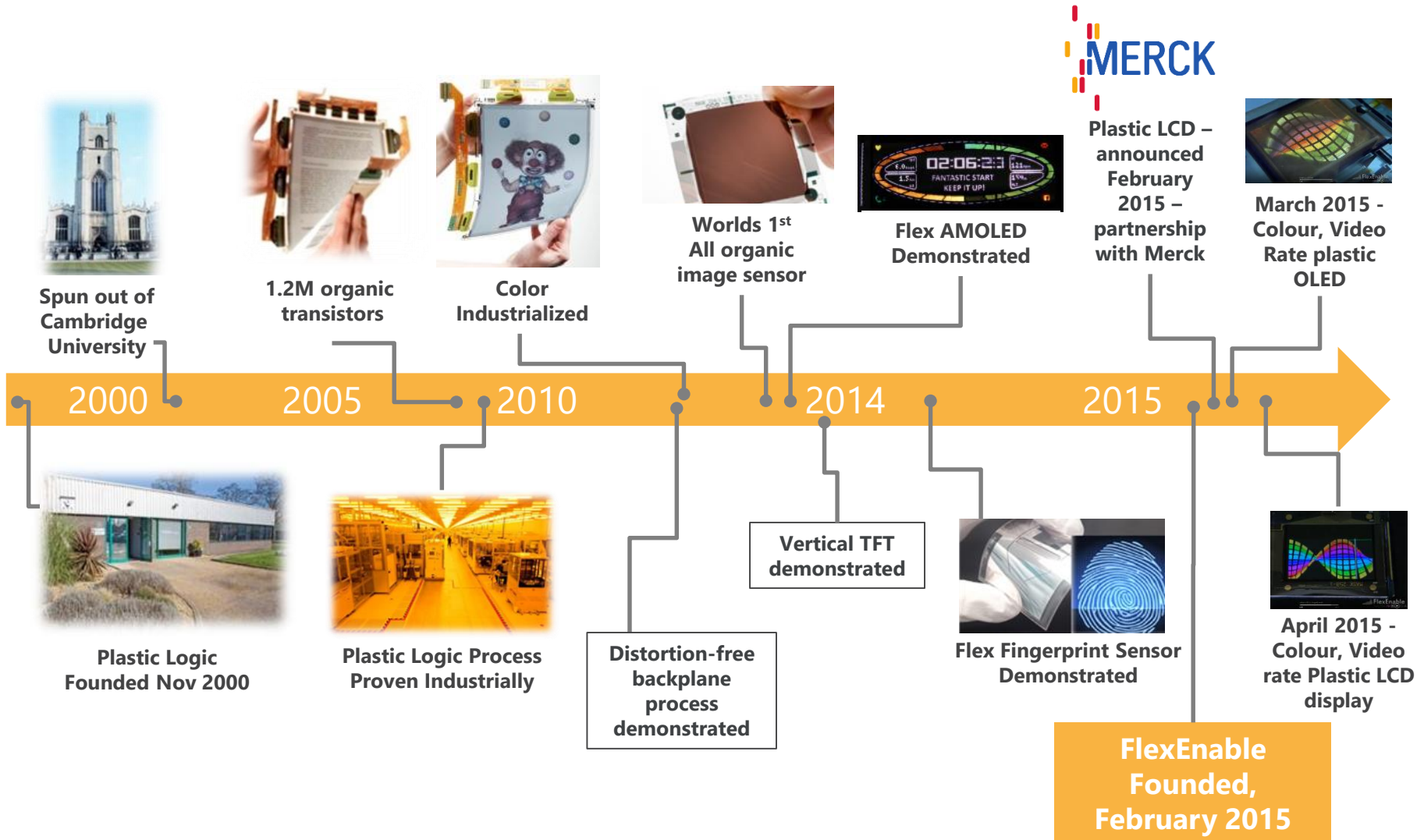


- Strong leadership and committed team
- Courageous and faithful investors

Lessons / challenges for commercialisation of early-stage materials technologies

- Investment **risk** due to long development timescale - Difficulty in anticipating evolution of technology competition and market needs
 - Identify and address key technology barriers as early as possible
 - Development needs to target future product requirements, not current ones.
- Proving a new materials technology requires significant **investment** in manufacturing infrastructure
 - Access to public facilities / foundries for prototyping / small-scale manufacturing; Manufacturing partnership with large company
- Establishing place in complex value chain **network**
 - It is very hard for a technology company to develop a consumer product.

FlexEnable now owns the Field of Plastic Electronics for Surfaces thanks to Plastic Logic's R&D and Manufacturing Investments



Driving the new era in flexible electronics



FlexEnable's proven technology platform enables customers to create compelling flexible electronics products and to manufacture these in volume

- IP Company owning all of the IP developed over last 15 years under PL – 133 patent families
- World's leading OTFT technology team – 38 engineers
- R&D/Prototyping Lab
- Focused on new mainstream applications – LCD, OLED, sensor arrays for IoT
- Lowest cost and most flexible platform for bringing surfaces to life
- Proven high-volume technology and experienced tech-transfer team

PLASTIC LOGIC

Plastic Logic Germany develops and manufactures flexible electrophoretic displays (EPDs) in a full range of sizes

Served with a Comprehensive Offering to Create a Supply Chain for Flexible Electronics

ProductEnable™

Monetisation: Fees from prototypes and projects`

Create and source product applications for truly flexible electronics



Product Design



Field Trials



Prototypes



Design of high volume production processes

MaterialsEnable™

Monetisation: Fees from materials testing and qualification

Asses and qualify new materials for flexible electronics



Test protocol definition



Mechanical testing and qualification



Process development



Demonstrators

FabEnable™

Monetisation: Transfer fees, licences and royalties

Tech transfer to upgrade existing fabs to make flexible electronics



Feasibility study



Process design



Process implementation



Process upgrades

Management Team

Leading the world's strongest and most experienced team of engineering talent for plastic electronics

Chuck Milligan

CEO

- Joined as CEO in May 2015, after taking PE-backed EM Test to exit
- CEO & Board Member of Heptagon
- Vice President of Industrial & Defense Solutions for Bookham Inc.
- EMEA Director of Sales at Harris Corporation



Dr Paul Cain

Strategy Director

- Over a decade in flexible electronics
- Deep knowledge of displays technologies and industry
- 25 patents for flexible electronics
- Physics PhD – University of Cambridge
- MBA – London Business School

Heads a team of 3



Dr Mike Banach

Technical Director

- Over a decade in flexible electronics
- Led the team that developed flexible OLED, LCD
- Transferred tech from lab to fab
- Physics PhD – University of Cambridge

Heads a team of 36



Simon Jones

Commercial Director

- Joined FlexEnable from Dow Corning where he led several major innovation programs as Business and Innovation Development Director
- Previous roles include VP Business Development at Liquivista (now part of Amazon) and VP Product Development at Plastic Logic



Dean Baker

FabEnable Director

- c.10yr in flexible electronics manufacturing and development
- Project Manager at BOC Edwards
- Previously engineering leadership at Nortel Networks, JDS Uniphase and e2v



James Newman

Finance Director

- 15 years experience in technology sector in UK and US in start up and quoted companies
- Chartered Accountant

Heads a team of 6



Headcount

▪ CEO	1
▪ Technical Team	36
▪ Strategy and MarCom Team	3
▪ Finance and Admin Team	6
▪ Commercial and FabEnable	2
Total:	48

Board of Directors



Indro Mukerjee
Non-Exec Chairman
Chairman & ex-CEO of
FlexEnable; CEO of Quindell



Chuck Milligan
CEO



Lord Alec Broers
Director
Member of the British
Parliament, President of the
Royal Academy of Engineering



Prof Henning Sirringhaus
Director
Hitachi Professor of Electron
Device Physics at the Cavendish
Laboratory



Dr Hermann Hauser
Director
Serial Entrepreneur and co-
founder of Amadeus Capital
Partners



Nikolay Tychinin
Director
Investment Director at Rusnano
Management Company LLC



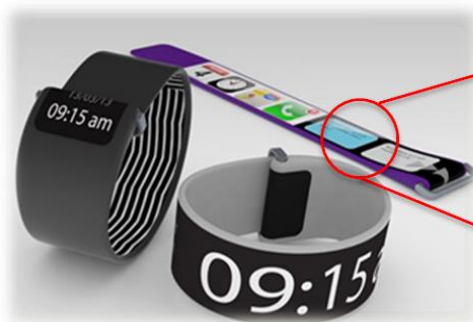
Dr Ronald Black
Director
President and CEO, Rambus Inc
– IP licensing



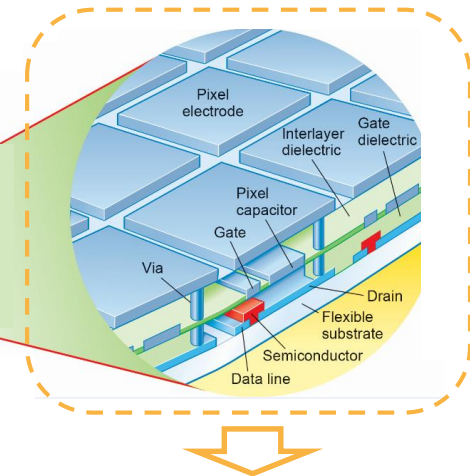
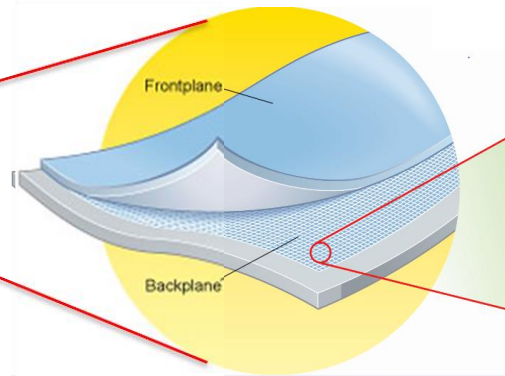
Yuriy Udaltsov
Advisor
Deputy Chairman of the
Executive Board at Rusnano
Management Company LLC

A Unique Technology Platform

- Building on more than a decade of development of **high performance** Organic Thin Film Transistor (OTFT) on flexible substrates
- **Fully industrialised** and suitable for manufacturing production
- Enables true flexibility, bendability and unbreakability – by combining FlexEnable backplane and with partners' frontplanes for **LCD, OLED, EP Displays, Sensors & entire electronics systems** on plastic



Flexible displays & Sensors



FlexEnable's value is the processes, architectures, materials and qualification IP to manufacture truly flexible electronics

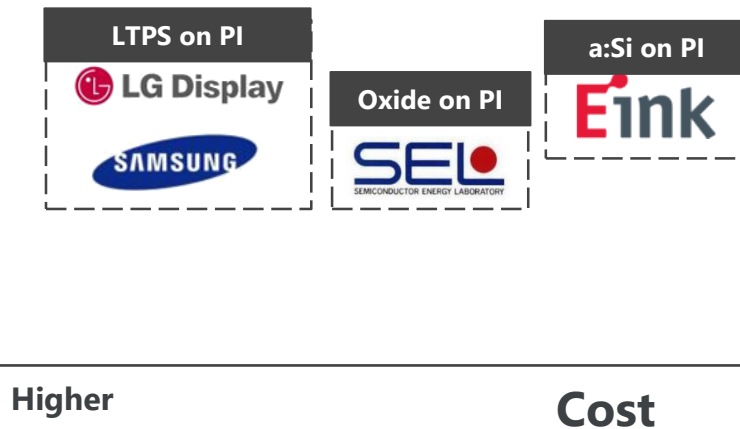
Best in-class Performance and Cost Advantages

More cost effective and more flexible than alternatives

Physical Characteristics

Robust (Shatterproof)
Ultra-thin/light,
Truly Flexible

Breakable,
Shapeable



60Hz OLED/LCD
Flexible full motion video

25µm
Substrate Thickness
As thin as a human hair

0.25mm
Transistor Bend Radius
Wraps around a matchstick

oTFT on PET
FlexEnable
Truly flexible electronics

< 100°C
Low Temperature
Lowest transistor
manufacturing temperature

\$↓
Low Cost
Lowest cost for all areas
and surfaces

100 gsm
Weight per area
As light as a sheet of paper

- **Today:**
 - The lowest cost flexible electronics array technology
 - The only truly flexible array technology
- **With volume: cost parity with glass LCD**
- **With Roll to Roll: a fraction of the cost of LCD**

What is needed for Plastic Electronics over Surfaces to take off?

Utility – What do you get with glass-free?

- ✓ Conformability
- ✓ Flexibility
- ✓ Thinness
- ✓ Light weight
- ✓ Unbreakable

Performance

- ✓ Transistors - Better than a:Si
- ✓ Uniformity
- ✓ Reliability

Cost/Volume

- ✓ BOM
- ✓ Yield
- ✓ Existing Manufacturing Infrastructure

OTFT
Low-Temperature Process

Organic Semiconductor
Solution Processing

Low-Temperature Process
FPD Compatible

All the Boxes are Checked – the future is now for LowTemp OTFT Arrays

Enabling a Wide Range of Applications

Wearables / Displays



Displays on wearables



Automotive displays



Smartphones

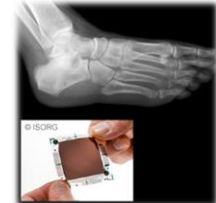


OLED Smartwatch

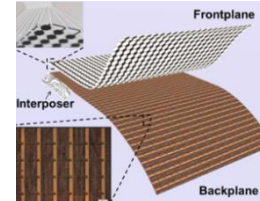
Sensors



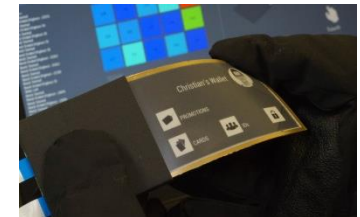
Fingerprint and vein sensor



X-ray sensor



Pressure Sensor Array



New user interface pressure and strain

System Solutions



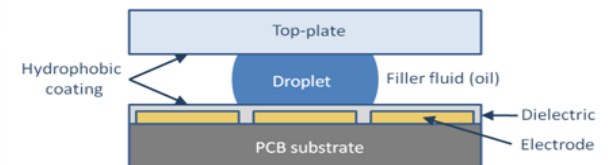
Multi-function Printed Smartcard



Smartcard with display and sensor



Gas sensors: CO, H₂S, O₂



Lab on Chip

Flexible Displays for Wearables and Everywhere-ables

Enabling New markets and transforming existing markets

Unbreakable Mobile Devices



Automotive and Aerospace



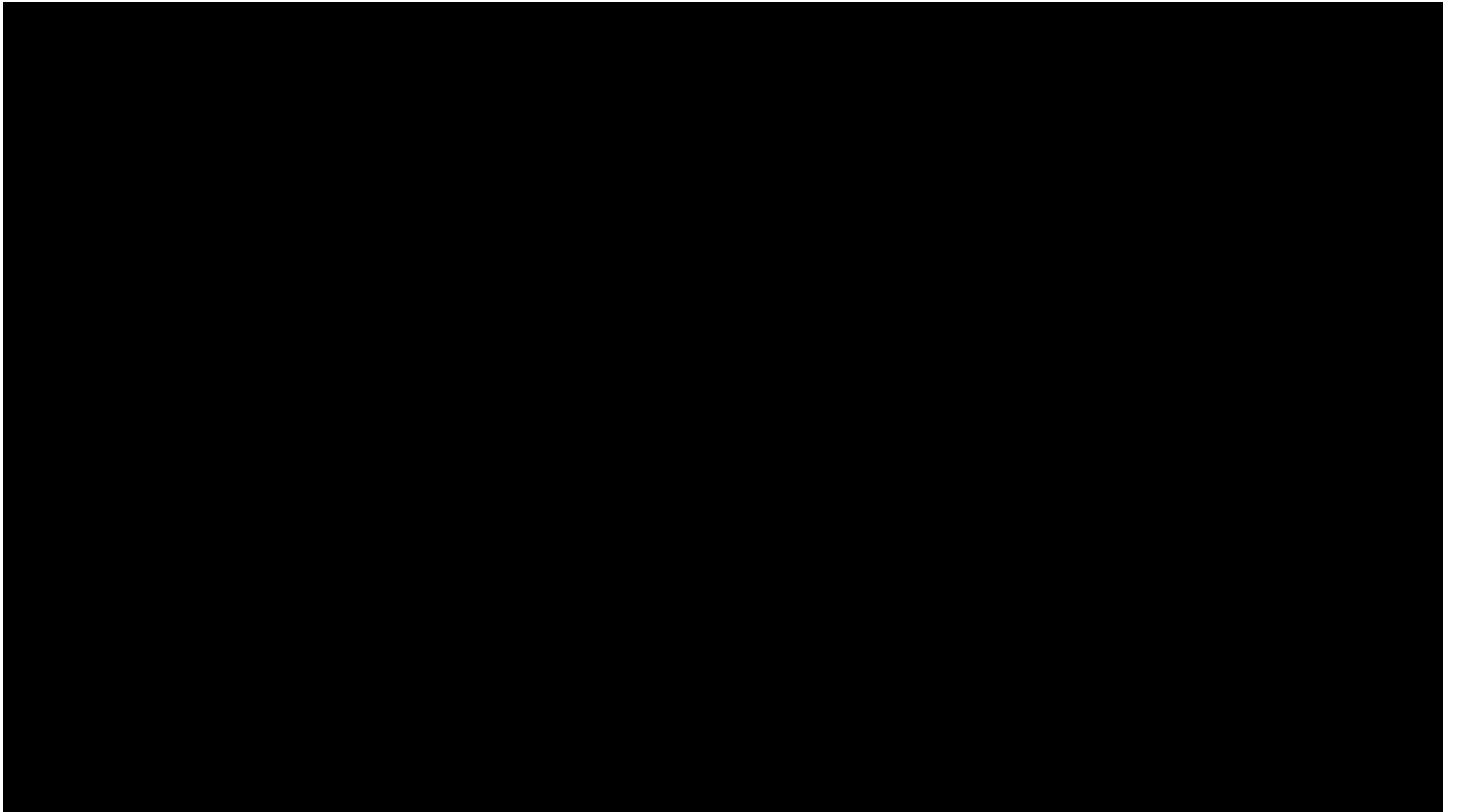
Wearables



Digital Signage



Full Colour OLCD



In partnership with



Flexible Colour OLED in partnership CPT

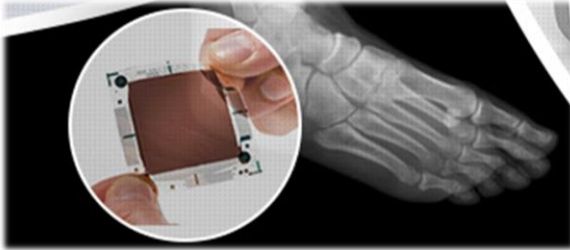


 **FlexEnable**
Truly flexible electronics

Glass-free Wearable and Everywhere-able Sensors

Enabling New markets and transforming existing markets

Flexible, Unbreakable
Xray Sensors



Multi-functional
Smartcards



Wearable Sensors



Flexible, Wearable
Biometrics

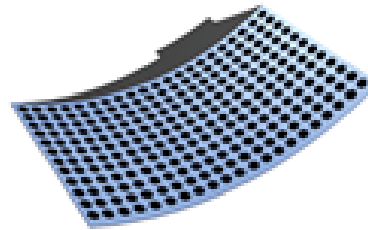


Pressure Sensor Arrays for "Electronic Skin"

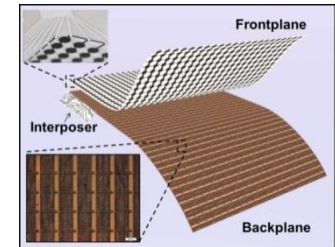


Printed Plastic OTFT
array backplane

+



Printed Piezoelectric
Pressure sensor



Pressure sensor array

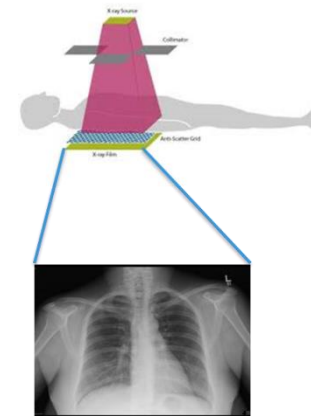
Flexible X Ray Sensors

- Shatterproof, with near zero incremental thickness and weight
- Enables X-ray systems to go anywhere – to road traffic accidents, around pipework, mobile systems
- Conformable around the body – improves accuracy and patient comfort

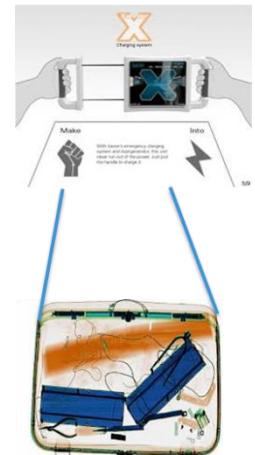


Industry Applications

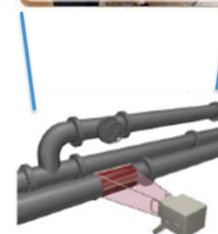
Medical



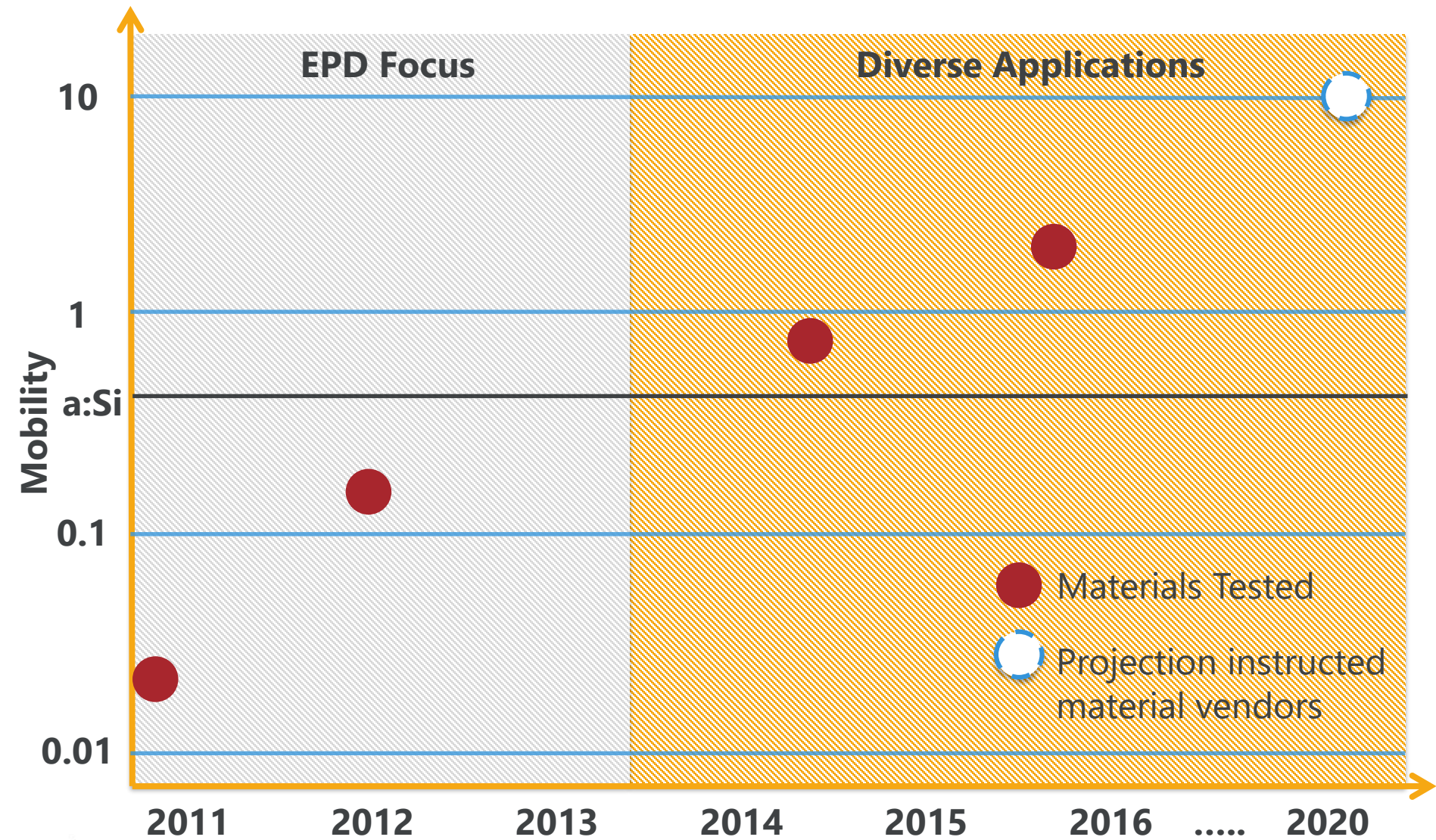
Security



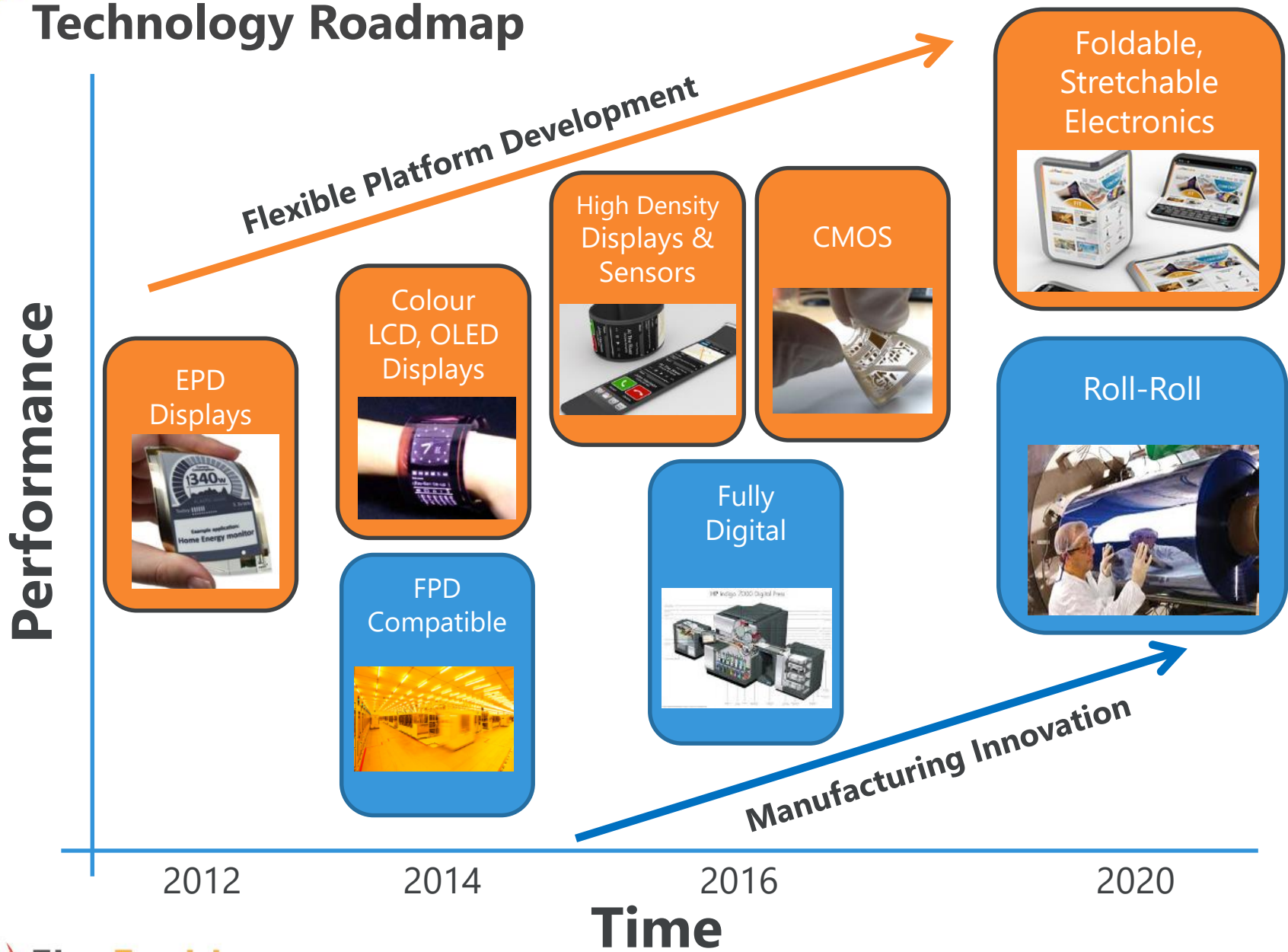
Oil & Gas



Mobility Performance Progression



Technology Roadmap

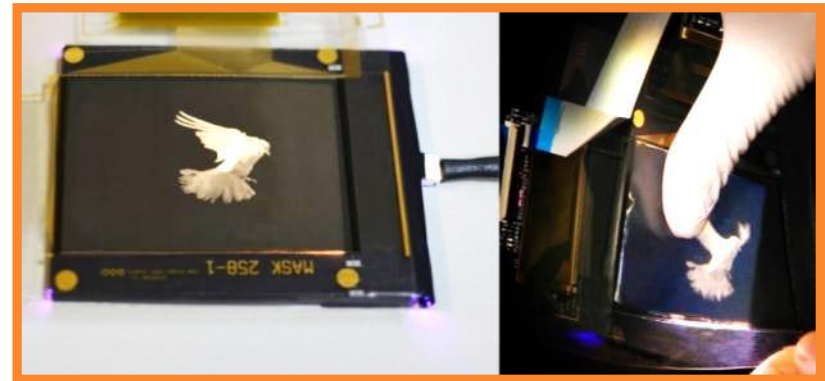


FabEnable: Plastic LCD Brings Superior Production Economics



Traditional Approach

- **Expensive substrate** = Fiber reinforced plastic (FRP) ~ \$100/sqm
- **Glass is destroyed** during cell assembly process
- **Not a practical process** for volume manufacturing



FlexEnable Approach

- Substrate **100X lower cost**: Triacetyl Cellulose (TAC) ~ \$1/sqm
- **Glass removed from BOM** (re-used in the line)
- Process **industrially proven** for volume manufacture.

Repurposing existing Assets and supply chains

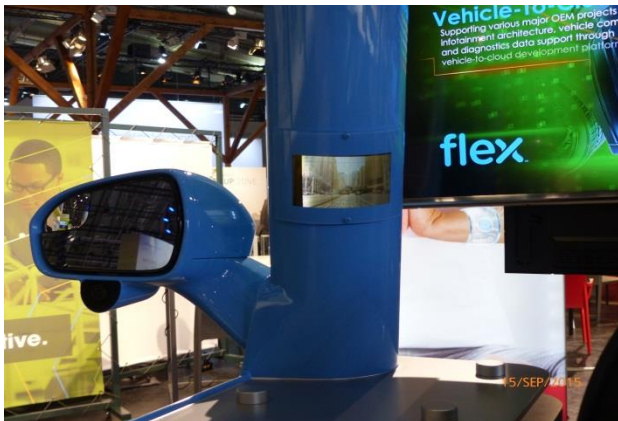
Existing a:Si Supply Chain and production facilities



Organic Dielectric
Organic Semiconductor



Low cost, conformable OLCD



Flexible Barrier Layers



Truly Flexible and Foldable AMOLED



A few take-aways

- For a technology start-up, especially in hardware/manufacturing, too narrow a focus prior to real commercial traction can lose huge time and money and potentially lead to ruin
- There are several leaps from technology to a commercial product. From technology to product to manufacturing to commercial success. As a start-up, if the leaps are big and there is no one pulling/guiding, the probability of success is small. The chance of success gets much higher when an established player in your target market has skin-in-the-game.
- Management need to think like owners. Management needs to own strategy, with investor buy-in, and re-validate strategy constantly.
- Survival may depend on flexibility in business model – requiring courage and clear strategic vision to reorganise company and adjust to changes in industry/market before it is too late
- Never lose track of the customer – his voice needs to be heard in every meeting and play a part in every decision
- FlexEnable now has a business model based on industrial partnerships and technology licensing – enabled by the convergence of proven technical capability and a validated market demand for the benefits of plastic electronics



Thank You